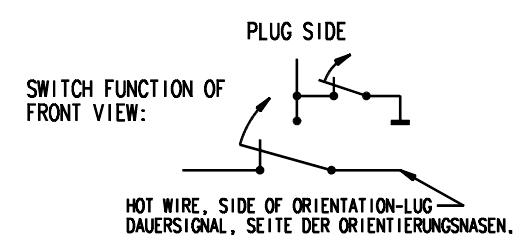
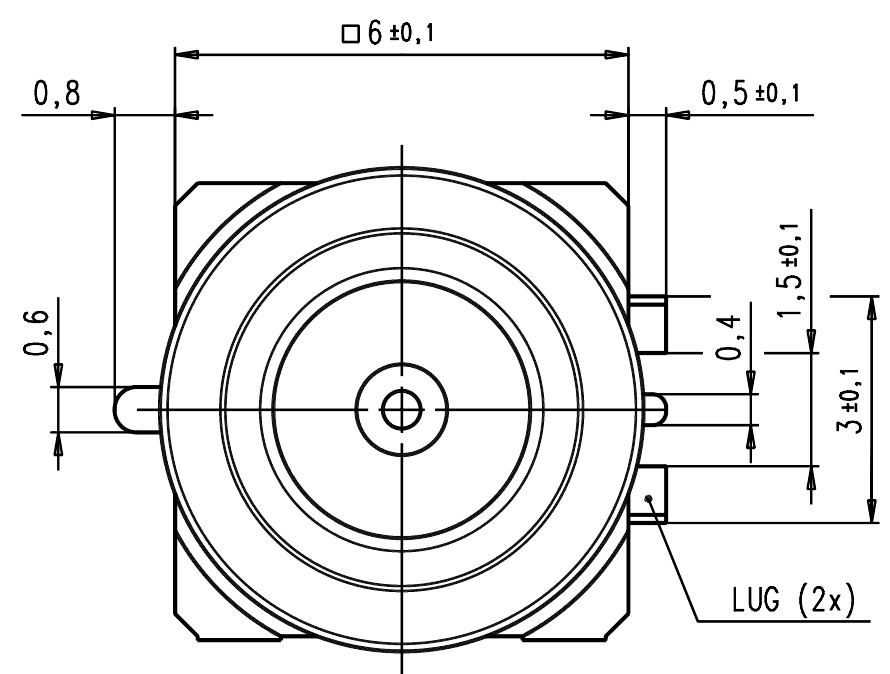
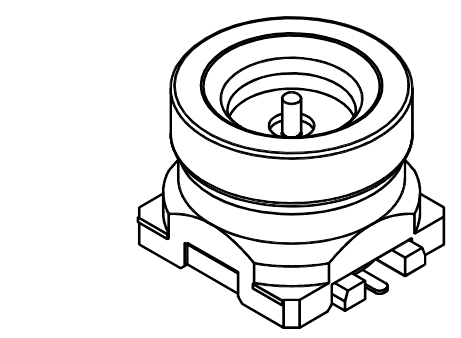
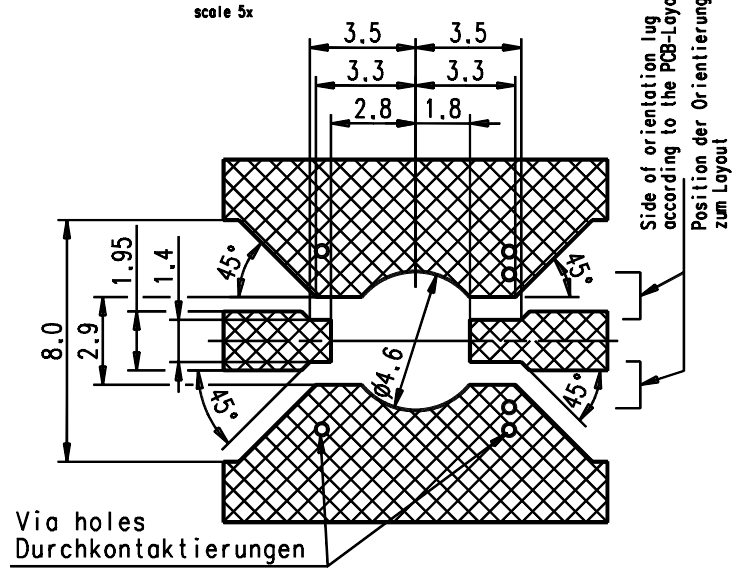


MATERIAL UND BESCHICHTUNG:		
GEHAEUSE	GD-ZnAl4Cu1	OPTALLOY & FLASH Au
ISOLIERUNG	PA46	
FEDERN	CuBe2	Au
DICHTUNG	SILICON	
RESTTEILE	CuZn39/B05	Au
MATERIAL AND PLATING:		
HOUSING	GD-ZnAl4Cu1	OPTALLOY & FLASH Au
INSULATOR	PA46	
SPRING	CuBe2	Au
GASKET	SILICON	
OTHER PARTS	CuZn39/B05	Au



Multilayer PCB under Switch should be matched to 50 Ohm
SMT-Solderpad Layout proposal
SMT-Loetflaechen:



- NOTE:
1. SWITCH HAS TO BE SOLDERED TO PCB USING SMT TECHNOLOGY PRIOR TO CONNECTION WITH MATING HALF.
 2. MAXIMUM HEAT WHICH CAN BE APPLIED TO THE SWITCH IS 250°C.
 3. DATUM LEVEL IS THE SWITCH HOUSING. THE COPLANARITY OF ALL SOLDER SURFACES MUST BE WITHIN -0,03 TO +0,07 mm.

					general tolerance	ISO 2768	scale: 10:1
					ISO 2768	-m	
					0,5-3: ±0,1	Assembly instruction:	
					3-6: ±0,1	Stripping dimension:	
					6-30: ±0,2		
					date	name	
					generate	30.11.99	Zech
					checked		
017/03	e	revised	16.01.03	ze	Norm	SMT Schalter	
183/02	d	Koplanarität	11.03.02	ze	31686	SMT Switch	
341/00	c	Interface	10.05.00	ze			
ENTWURF	b	UEBERARBEITUNG	04.02.00	ze		2909.99.0030.00'	
ENTWURF	a	UEBERARBEITUNG	09.12.99	ze		Rev. e	
nr.	rev.	alteration	date	name			